

FIG. 1

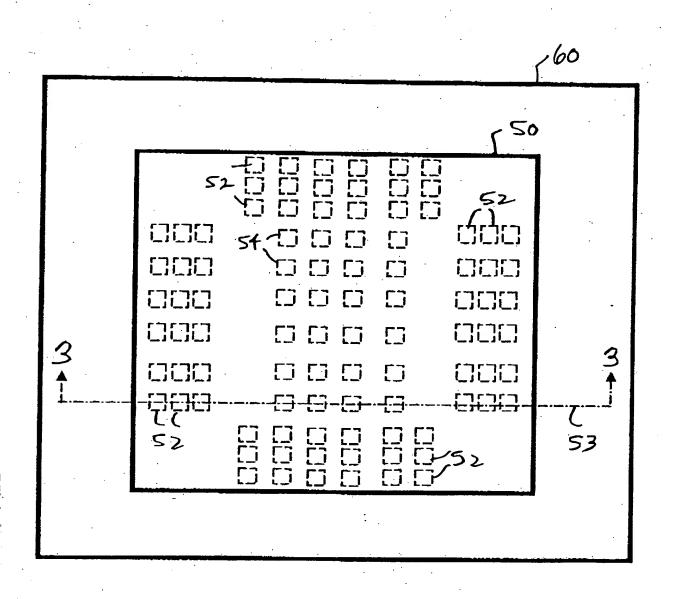


FIG. 2 (PRIOR ART)

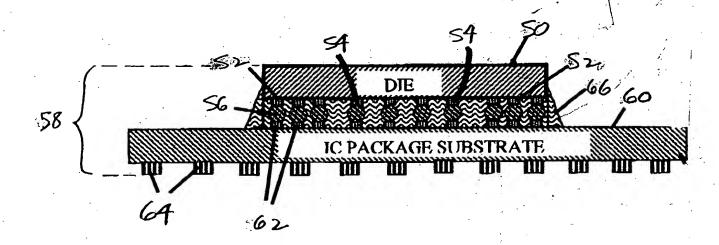


FIG. 3 (PRIOR ART)

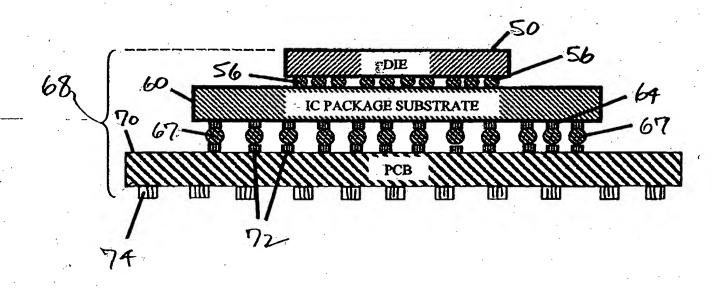


FIG. 4 (PRIOR ART)

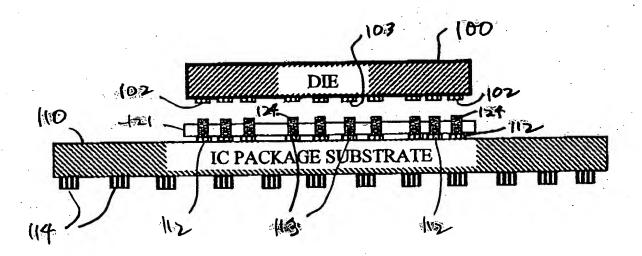


FIG. 5

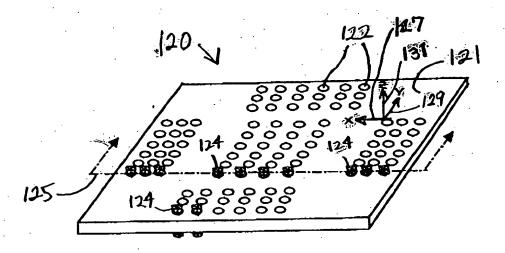


FIG. 6

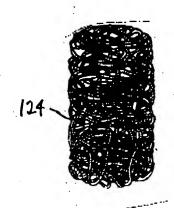


FIG. 7

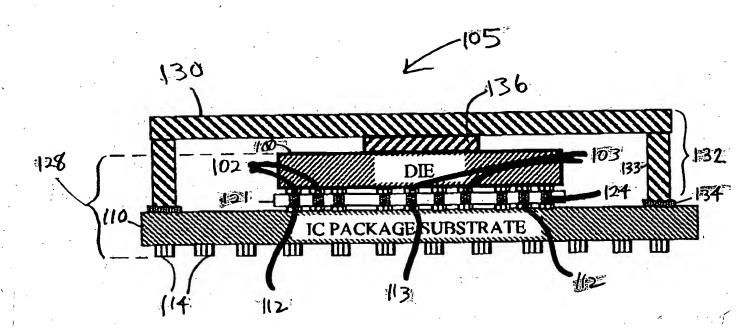
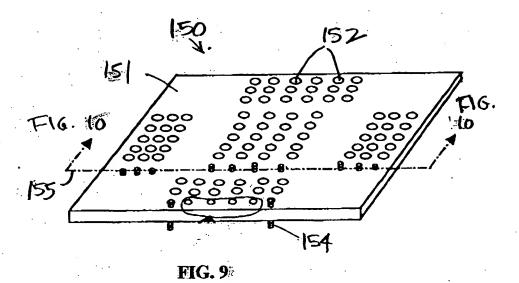


FIG. 8



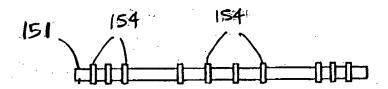


FIG. 10

160

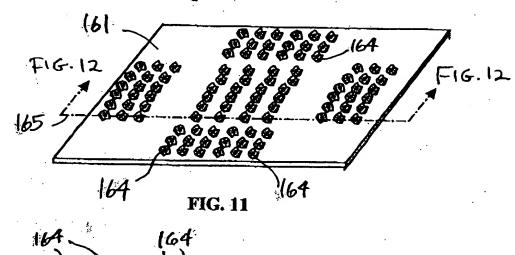


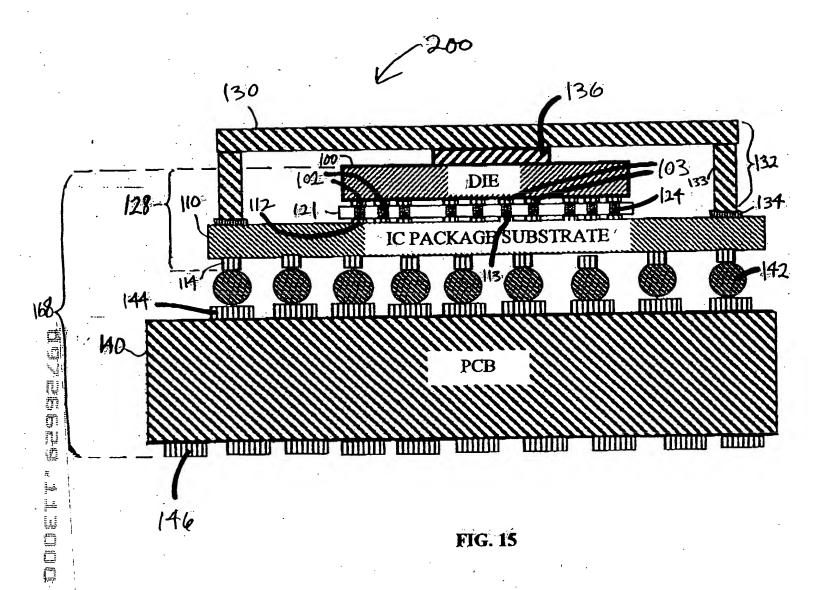
FIG. 12 %

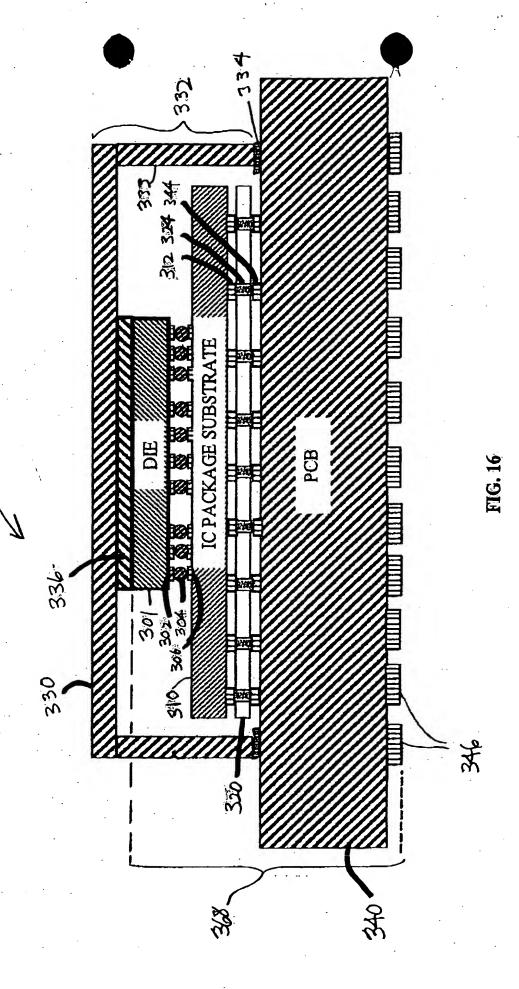


FIG. 14



FIG. 13





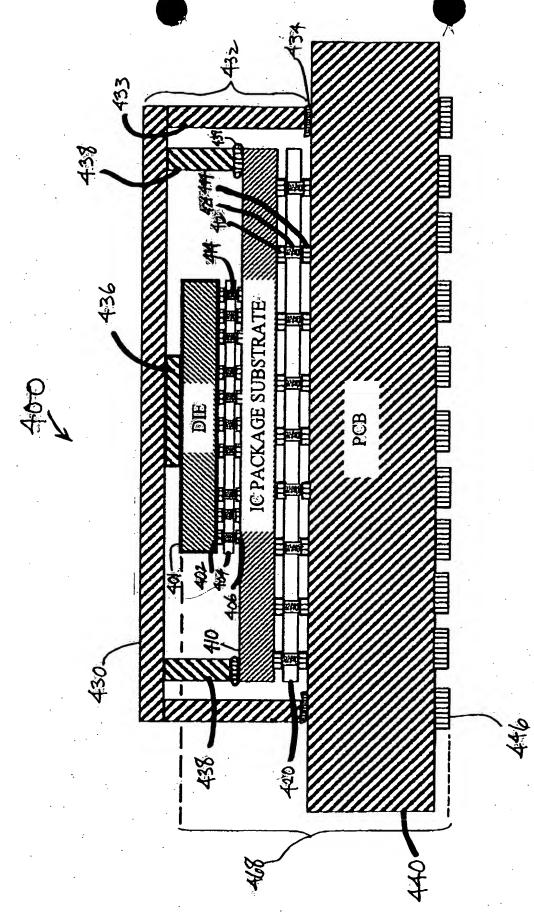


FIG. 17



222

PROVIDE A CONNECTOR HAVING A PLURALITY OF ELECTRICALLY CONDUCTIVE ELEMENTS (ECEs) IN A THIN, FLEXIBLE, ELECTRICALLY INSULATING SUPPORT. THE ECEs CAN BE, FOR EXAMPLE, WIRE WADS, PINS, OR CRYSTALS. THE SUPPORT CAN BE, FOR EXAMPLE, A PLASTIC SHEET OR A RESIN FILM.

224-

COUPLE LANDS ON AN IC OR ON AN IC PACKAGE TO CORRESPONDING LANDS ON A SUBSTRATE WITH THE ELECTRICALLY CONDUCTIVE ELEMENTS

226

COMPRESS AND SECURE THE IC OR IC PACKAGE, THE SUPPORT, AND THE SUBSTRATE IN A PACKAGE, FOR EXAMPLE, USING AN INTEGRATED HEAT SPREADER THAT INCLUDES A COMPRESSION ELEMENT

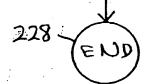


FIG. 18



242-

POSITION A THIN, FLEXIBLE, ELECTRICALLY INSULATING SUPPORT ON A SUBSTRATE, SO THAT A PLURALITY OF ELECTRICALLY CONDUCTIVE ELEMENTS (ECEs) ON THE SUPPORT ARE ALIGNED WITH RESPECT TO A CORRESPONDING PLURALITY OF LANDS ON THE SUBSTRATE

2447

POSITION AN IC OR IC PACKAGE ON THE SUPPORT, SO THAT A PLURALITY OF LANDS ON THE IC OR IC PACKAGE ARE ALIGNED WITH RESPECT TO A CORRESPONDING PLURALITY OF ECEs ON THE SUPPORT

2467

POSITION A THIN, FLEXIBLE, ELECTRICALLY INSULATING SUPPORT ON AN IC OR IC PACKAGE, SO THAT A PLURALITY OF ECES ON THE SUPPORT ARE ALIGNED WITH RESPECT TO A CORRESPONDING PLURALITY OF LANDS ON THE IC OR IC PACKAGE

2487

POSITION THE SUPPORT ON A SUBSTRATE, SO THAT A PLURALITY OF LANDS ON THE SUBSTRATE ARE ALIGNED WITH RESPECT TO A CORRESPONDING PLURALITY OF ECEs ON THE SUPPORT

250-

COMPRESS THE IC OR IC PACKAGE, THE SUPPORT, AND THE SUBSTRATE TOGETHER TO MAINTAIN ELECTRICAL CONTACT BETWEEN THE LANDS ON THE IC OR IC PACKAGE AND THE LANDS ON THE SUBSTRATE

